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ie		Drilled hole Ø	1,15±0,025 mm	A
	Tin plated PCB (HAL) acc. to EN 60352-5	Sn	max. 15 µm	
	all. TO LN 00552-5	plated hole Ø	0,94 - 1,09 mm	
Γ		Drilled hole Ø	1,15±0,025 mm	
	Chemical tin plated PCB	Sn	min. 0,8µm	
-		plated hole Ø	1,00 - 1,10 mm	
	-	Drilled hole Ø Ni	1,15±0,025 mm 3 – 7 μm	
	Gold /Nickel plated PCB	Au	0,05 – 0,12 μm	
	ł	plated hole Ø	1,00 – 1,10 mm	
T		Drilled hole Ø	1,15±0,025 mm	
	Silver plated PCB	Ag	0,1 - 0,3 µm	
L		plated hole Ø	1,00 – 1,10 mm	B
	Copper plated PCB (OSP)	Drilled hole Ø plated hole Ø	1,15±0,025 mm 1,00 - 1,10 mm	
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